

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	437	(oxygen or ozone or o3) near9 plasma near9 wir\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 10:17
L2	10	(oxygen or ozone or o3) near9 plasma near9 wir\$4 near9 (chip or element)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 09:25
L3	4	(oxygen or ozone or o3) near9 plasma near9 wir\$4 near9 gold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 09:35
L4	1	"6090696".pn.	USPAT	OR	ON	2005/01/03 09:36
L5	12	(oxygen or ozone or o3) near9 plasma near9 wir\$4 near9 clean\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 10:01
L6	94	(oxygen or ozone or o3) near9 plasma near9 wir\$4 and clean\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 10:27
L7	39	I6 not I5 and bond\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 10:18
L8	25	(oxygen or ozone or o3) near9 plasma near9 encapsula\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 10:38
L9	656	(oxygen or ozone or o3) near9 plasma near9 polyimide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 10:39
L10	293	(oxygen or ozone or o3) near9 plasma near9 polyimide and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 10:40

L11	6	(oxygen or ozone or o3) near9 plasma near9 polyimide near9 chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 10:40
L12	13	("5807787").URPN.	USPAT	OR	OFF	2005/01/03 10:47
L13	9	("4493855" "4599243" "4622574" "4732658" "5229324" "5364806" "5414287" "5492863" "5494838").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/03 10:53
S1	522	438/597.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/03 09:18
S2	37	438/597.ccls. and resin and plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 15:16
S3	42	438/124.ccls. and plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 15:16
S4	0	(438/597.ccls. and resin and plasma) and (438/124.ccls. and plasma) and ((irradiating or plasma) same resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 15:17
S5	43	(438/597.ccls. and resin and plasma) or (438/124.ccls. and plasma) and ((irradiating or plasma) same resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 15:17
S6	6	((438/597.ccls. and resin and plasma) or (438/124.ccls. and plasma) and ((irradiating or plasma) same resin)) and rough\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 15:36
S7	4	"6,596,559"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 16:02
S8	2548	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/22 16:05

S9	41	438/106.ccls. and rough\$6 and plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 13:55
S10	0	"6713858".URPN.	USPAT	OR	OFF	2004/06/22 17:21
S11	27	("3013926" "4211824" "4251409" "4388132" "4680228" "5002808" "5098618" "5104944" "5121190" "5147084" "5391650" "5583747" "5683757" "5745984" "5948484" "6074895" "6248614" "6259155" "6284050" "6288900" "6294741" "6353420" "6512295" "6548909" "6596559" "6624507" "6642613").PN.	USPAT	OR	OFF	2004/06/22 17:23
S12	481	"438"/\$5.ccls. and resin and (openings same pads)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 10:26
S13	407	("438"/\$5.ccls. and resin and (openings same pads)) and (chip or die) and (top or over or covering)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 10:26
S14	104	((("438"/\$5.ccls. and resin and (openings same pads)) and (chip or die) and (top or over or covering)) and exposing same pads	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 10:27
S15	32	((("438"/\$5.ccls. and resin and (openings same pads)) and (chip or die) and (top or over or covering)) and exposing same pads) and encapsulating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 10:27
S16	3	((("438"/\$5.ccls. and resin and (openings same pads)) and (chip or die) and (top or over or covering)) and exposing same pads) and encapsulating) and (O2 or oxygen)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 10:28
S17	2	"6689641".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 12:26

S18	13	(US-6074895-\$ or US-5002808-\$ or US-6713858-\$ or US-6248655-\$ or US-6600224-\$ or US-6596559-\$ or US-6602803-\$ or US-5766979-\$ or US-6512295-\$ or US-4388132-\$ or US-6479409-\$ or US-6689641-\$). did. or (US-20020130397-\$).did.	US-PGPUB; USPAT	OR	OFF	2004/06/23 12:51
S19	1	((US-6074895-\$ or US-5002808-\$ or US-6713858-\$ or US-6248655-\$ or US-6600224-\$ or US-6596559-\$ or US-6602803-\$ or US-5766979-\$ or US-6512295-\$ or US-4388132-\$ or US-6479409-\$ or US-6689641-\$). did. or (US-20020130397-\$).did.) and (inert or helium or argon or neon).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 12:52
S20	4	((US-6074895-\$ or US-5002808-\$ or US-6713858-\$ or US-6248655-\$ or US-6600224-\$ or US-6596559-\$ or US-6602803-\$ or US-5766979-\$ or US-6512295-\$ or US-4388132-\$ or US-6479409-\$ or US-6689641-\$). did. or (US-20020130397-\$).did.) and (inert or helium or argon or neon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 12:53
S21	0	JP2001-230527	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/06/23 16:40
S22	7704	(438/15 or 438/106 or 438/118 or 438/108 or 438/121 or 438/778 or 438/780 or 438/790 or 438/780). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 11:52
S23	5	((438/15 or 438/106 or 438/118 or 438/108 or 438/121 or 438/778 or 438/780 or 438/790 or 438/780). ccls.) and (plasma adj irradiating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 11:59
S24	1210	((438/15 or 438/106 or 438/118 or 438/108 or 438/121 or 438/778 or 438/780 or 438/790 or 438/780). ccls.) and voltage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:00
S25	61	((438/15 or 438/106 or 438/118 or 438/108 or 438/121 or 438/778 or 438/780 or 438/790 or 438/780). ccls.) and voltage) and (voltage same rf same plasma)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:00

S26	30	(((((438/15 or 438/106 or 438/118 or 438/108 or 438/121 or 438/778 or 438/780 or 438/790 or 438/780). ccls.) and voltage) and (voltage same rf same plasma)) and (resin or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:01
S27	28	(((((438/15 or 438/106 or 438/118 or 438/108 or 438/121 or 438/778 or 438/780 or 438/790 or 438/780). ccls.) and voltage) and (voltage same rf same plasma)) and (resin or polymer)) and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:11
S28	0	((438/15 or 438/106 or 438/118 or 438/108 or 438/121 or 438/778 or 438/780 or 438/790 or 438/780). ccls.) and (backside adj conductive adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:11
S29	1	(((((438/15 or 438/106 or 438/118 or 438/108 or 438/121 or 438/778 or 438/780 or 438/790 or 438/780). ccls.) or 438/597) and (backside adj conductive adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:14
S30	11	"438"/\$5 and (backside adj conductive adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:24
S31	80	conductive same polymer same substrate same bias	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:25
S32	23	(conductive same polymer same substrate same bias) and conductive and plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:37
S33	15	("4333793" "5001083" "5087857" "5362358" "5368685" "5439849" "5441595" "5468341" "5614060" "5683517" "5683538" "5877032" "5895740" "5942446" "6251791").PN.	USPAT	OR	OFF	2004/07/02 12:34
S34	0	(irradiat\$3 adj plasma) same (voltage same conductive same backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:38

S35	0	(irradiat\$3 adj plasma) and (voltage same conductive same backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:39
S36	0	(irradiat\$3 same plasma) and (voltage same conductive same backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:39
S37	0	(irradiat\$3 same plasma) and (bias same conductive same backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:39
S38	8	(irradiat\$3 same plasma) and bias and (conductive same backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 13:02
S39	7	((irradiat\$3 same plasma) and bias and (conductive same backside)) and voltage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:39
S40	31	(irradiat\$3 same plasma) and ((metal or conductive) same backside) and (resin or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:49
S41	53	(expos\$3 same plasma same (polymer or resin)) and ((metal or conductive) same backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 12:49
S42	4	((irradiat\$3 or expos\$3) same plasma) and ((connection same backside) same (cathode or anode))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 13:03
S43	159252	(USUI or HIDEKI or IGARASHI or SAKAMOTO).in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 13:43
S44	215	((USUI or HIDEKI or IGARASHI or SAKAMOTO).in.) and plasma same irradiat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 13:43

S45	74	((((USUI or HIDEKI or IGARASHI or SAKAMOTO).in.) and plasma same irradiat\$3) and (resin or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 13:44
S46	5	(((((USUI or HIDEKI or IGARASHI or SAKAMOTO).in.) and plasma same irradiat\$3) and (resin or polymer)) and (resin or polymer) same (over or cover\$3) same (die or chip or IC or element or circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 13:45
S47	11	438/106.ccls. and irradiat\$3 same plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/07/02 13:55
S51	1	"5909633".pn.	USPAT	OR	OFF	2004/11/22 13:01
S52	13148	(438/15 or 438/106 or 438/108 or 438/121 or 438/121 or 438/169 or 438/200 or 438/597 or 438/612 or 438/689 or 438/690 or 438/702 or 438/778 or 438/780 or 438/790). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/22 13:14
S53	6	S52 and plasma near9 irradiat\$3 near9 wir\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/22 13:15
S54	1152	438/127.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:05
S55	0	S54 and 438/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:05
S56	706	438/15.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:01
S57	2	S56 and 438/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:01

S58	2755	438/106.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:01
S59	0	S58 and 438/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:01
S60	1122	438/108.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:02
S61	0	S60 and 438/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:02
S62	615	438/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:02
S63	0	S62 and 438/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:02
S64	339	438/617.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:06
S65	0	S64 and 438/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:06
S66	2320	438/612.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:08
S67	4	S66 and 438/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:08

S68	1296	438/689.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:08
S69	49	S68 and 438/710.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/11 15:09